

PCN Number: 1109  
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### Product/Process Change Notification (PCN)

**Customer:** NAM & ASIA Distributors

**Date:** 10/14/2013

**Customer Part # and/Allegro part #:** A8295SESTR-T

**Originator:** J. Hurley

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**Duration of Change:**

Permanent  Temporary (explain)

**Summary description of change:** Part Change:  Process Change: Other:

Allegro currently manufactures the A8295SESTR-T at wafer fab, Polar Semiconductor Inc. (PSI), Bloomington, MN, USA, with Gold Bond Wires. We will add a second source wafer fab known as United Microelectronics Corporation (UMC), Hsinshu, Taiwan, and change to Copper Bond Wires.

**What is the part or process changing from (provide details)?**

The A8295SESTR-T is manufactured at wafer fab, Polar Semiconductor Inc. (PSI), Bloomington, MN, USA, with Gold Bond Wires, using BCD Generation 5 technology.

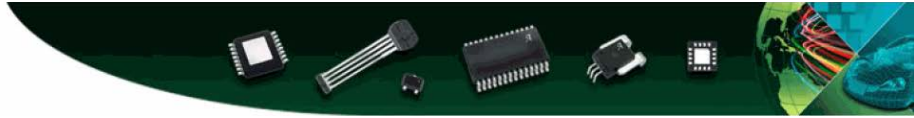
**What is the part or process changing to (provide details)?**

The A8295SESTR-T will be manufactured at wafer fab, United Microelectronics Corporation (UMC), Hsinshu, Taiwan, with Copper Bond Wires, using BCD Generation 6.5 technology.

**Describe how this change affects the customer:**

Allegro has performed the necessary qualification and electrical tests to ensure the device is functionally equivalent to the data sheet specification.





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**Expected completion date for internal qualification:** Complete

**Expected PPAP availability date:** N/A

**Target implementation date:** December 1, 2013

**Estimated date of first shipment:** January 1, 2014

**Expected sample availability date:** October, 2013

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**For Notification Only**

**Customer Approval Required:**

No

cc: Allegro Sales/Marketing/Quality